

MECHANICAL CASE OUTLINE

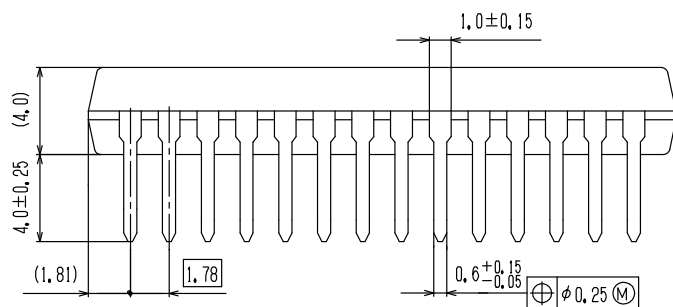
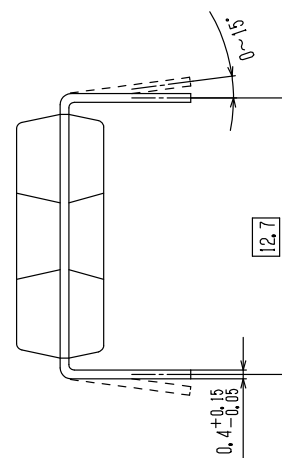
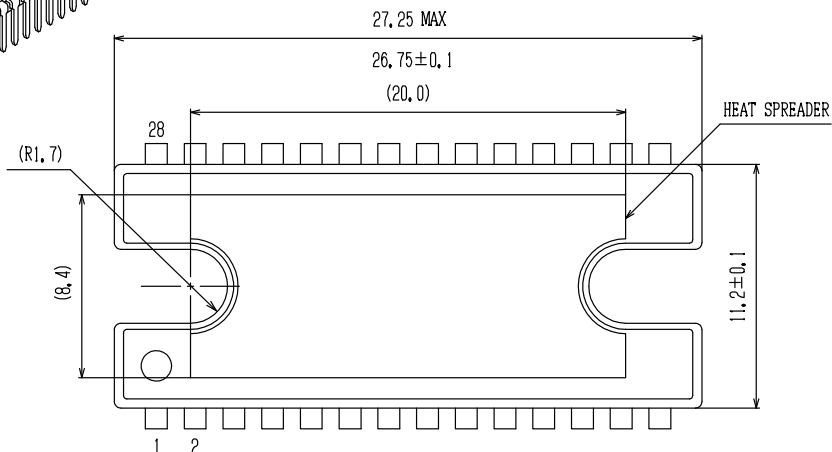
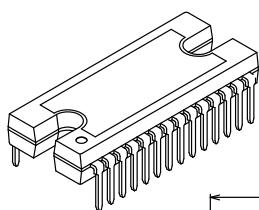
PACKAGE DIMENSIONS

ON Semiconductor®

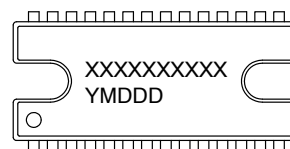


PDIP28 W/ HEAT SPREADER / DIP28H (500 mil) CASE 646AX ISSUE A

DATE 16 OCT 2013



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

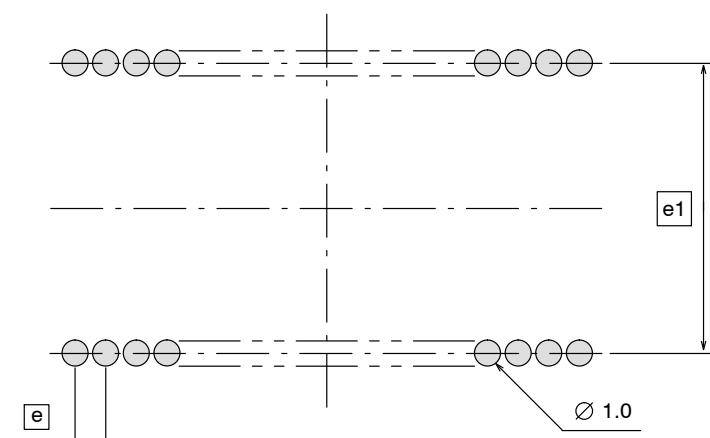
*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

(Unit: mm)

Reference symbol	Package name
	DIP28H (500 mil)
e1	12.70
e	1.78

○ Through Hole Area

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	PDIP28 26.75X11.2MM, 1.78P W/ HEAT SPREADER / DIP28H (500MIL)	PAGE 1 OF 1

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